

General Description

Features

The WSP9926B is the highest performance trench N-ch MOSFET with extreme high cell density, which provide excellent RDSON and gate charge for most of the small power switching and load switch applications.

The WSP9926B meet the RoHS and Green Product requirement with full function reliability approved.

• Advanced high cell density Trench technology

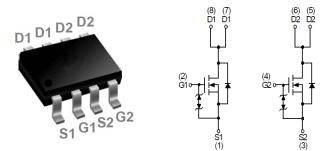
Product Summery

BVDSS	RDSON	ID
20V	17mΩ	8A

Applications

- High Frequency Point-of-Load Synchronous Small power switching for MB/NB/UMPC/VGA
- Networking DC-DC Power System
- ESD:2KV

SOP-8 Pin Configuration



Absolute Maximum Ratings

• Super Low Gate Charge

Excellent Cdv/dt effect declineGreen Device Available

Symbol	Parameter Rating		Units
V _{DS}	Drain-Source Voltage 20		V
V _{GS}	Gate-Source Voltage	±12	V
I _D @T _A =25℃	Continuous Drain Current, V _{GS} @ 4.5V ¹	8	А
I _D @T _A =70℃	Continuous Drain Current, $V_{GS} @ 4.5V^1$ 6.5		А
I _{DM}	Pulsed Drain Current ²	32	А
P _D @T _A =25℃	Total Power Dissipation ³	2	W
T _{STG}	Storage Temperature Range	-55 to 150	°C
TJ	Operating Junction Temperature Range	-55 to 150	°C

Thermal Data

Symbol	Parameter	Тур.	Max.	Unit
R _{ejA}	Thermal Resistance Junction-ambient ¹		62.5	°C/W
R _{θJC}	Thermal Resistance Junction-Case ¹		10	℃/W



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Dual N-Channel MOSFET

Electrical Characteristics (T_=25	°C, unless otherwise noted)
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Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	20			V
$\triangle BV_{DSS} / \triangle T_J$	BVDSS Temperature Coefficient	Reference to 25 $^\circ\!\!\mathrm{C}$, I_D=1mA		0.022		V/℃
Б	Static Drain-Source On-Resistance ²	V _{GS} =4.5V , I _D =8A		17	26	mΩ
R _{DS(ON)}		V _{GS} =2.5V , I _D =6.8A		25	34	
V _{GS(th)}	Gate Threshold Voltage		0.5	0.7	1.1	V
$ riangle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient	$V_{GS} = V_{DS}$, $I_D = 2500A$		-2.33		mV/℃
	Drain-Source Leakage Current	V_{DS} =16V , V_{GS} =0V , T _J =25 $^{\circ}$ C			1	
I _{DSS}		V _{DS} =16V , V _{GS} =0V , T _J =55℃			5	uA
I _{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm$ 12V , V_{DS} =0V			±100	nA
gfs	Forward Transconductance	V _{DS} =5V , I _D =5A		25		S
Rg	Gate Resistance	V _{DS} =0V , V _{GS} =0V , f=1MHz		4.5		Ω
Qg	Total Gate Charge (4.5V)	V _{DS} =10V , V _{GS} =4.5V , I _D =8A		11.3	17	
Q _{gs}	Gate-Source Charge			2.7		nC
Q _{gd}	Gate-Drain Charge			3.5		
T _{d(on)}	Turn-On Delay Time			5.2	9.5	
Tr	Rise Time	V_{DD} =10V , V_{GS} =4.5V , R_{G} =6 Ω		13.2	24	1
T _{d(off)}	Turn-Off Delay Time	I _D =5A ,R _L =10Ω.		40.5	73	ns
T _f	Fall Time			21.5	39	
Ciss	Input Capacitance	V _{DS} =10V , V _{GS} =0V , f=1MHz		650		
C _{oss}	Output Capacitance			140		pF
C _{rss}	Reverse Transfer Capacitance			135		

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
ls	Continuous Source Current ^{1,4}				1	А
I _{SM}	Pulsed Source Current ^{2,4}	$V_G = V_D = 0V$, Force Current			32	А
V _{SD}	Diode Forward Voltage ²	V _{GS} =0V , I _S =1A , T _J =25℃			1.3	V
t _{rr}	Reverse Recovery Time			19.2		nS
Qrr	Reverse Recovery Charge	IF=8A , dl/dt=100A/ μs , T _J =25 $^{\circ}$ C		4.6		nC

Note :

1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper,t<10sec.

2.The data tested by pulsed , pulse width $\leq 300us$, duty cycle $\leq 2\%$ 3.The power dissipation is limited by 150 $^\circ\!C\,$ junction temperature

4. The data is theoretically the same as I_{D} and I_{DM} , in real applications , should be limited by total power dissipation.



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Typical Characteristics

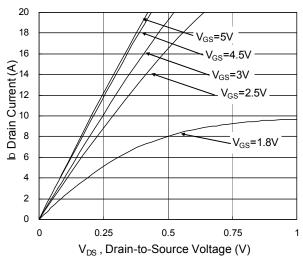


Fig.1 Typical Output Characteristics

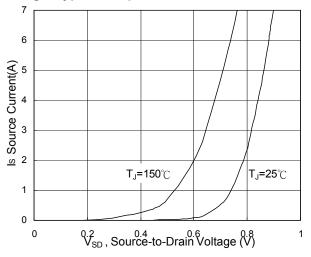


Fig.3 Forward Characteristics Of Reverse

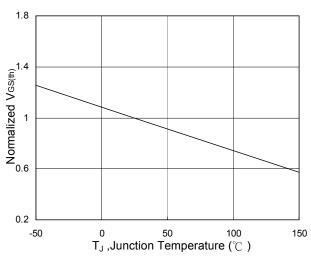


Fig.5 Normalized $V_{GS(th)}$ vs. T_J

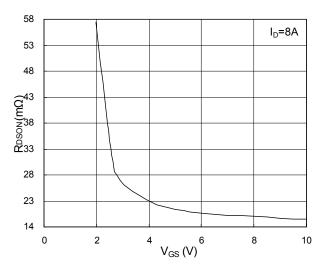


Fig.2 On-Resistance vs. Gate-Source

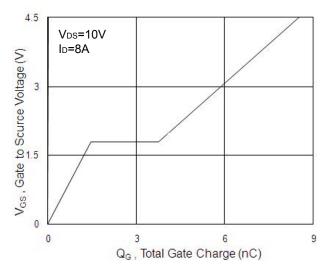


Fig.4 Gate-Charge Characteristics

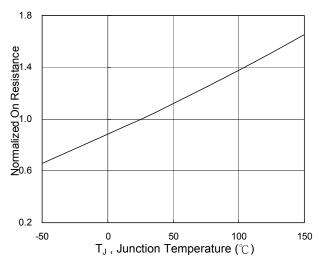
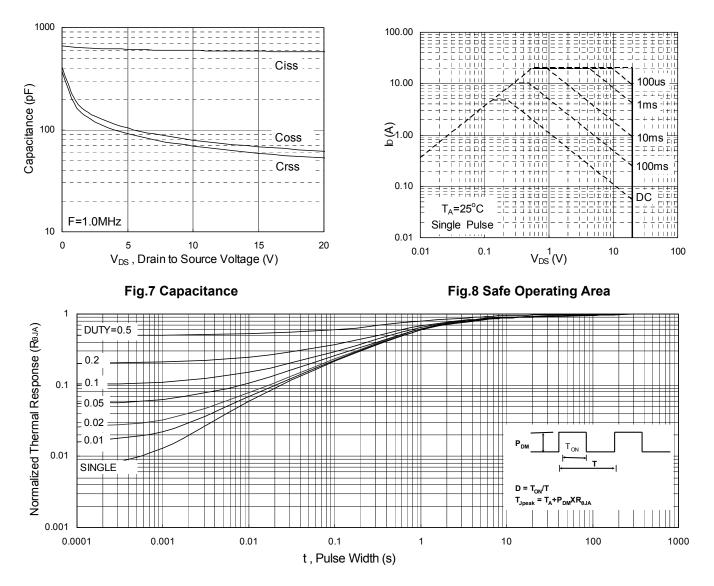


Fig.6 Normalized R_{DSON} vs. T_J

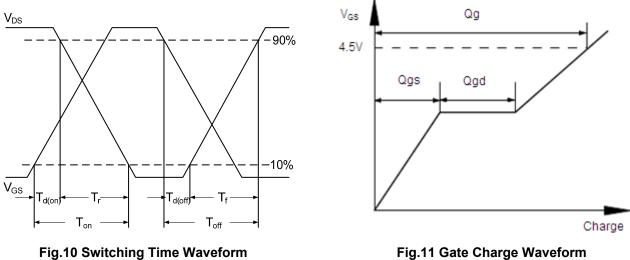


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